

Travelling Merchant: _____

DATASHEET

Standard: M11A-BCAC-38.88MHz

Plot			The Label
Drawing	Auditing	Approve	Stamp, please! Thanks!
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Date: 2009-06-26			

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The parameter of product

MODEL: M11A-BCAC-38.88MHz

1. Output

1.1. Nominal Frequency	38.88MHz
1.2. Waveform	HCMOS
	$V_{oh} \geq 2.7V$, $V_{ol} \leq 0.4V$
1.3. Duty cycle	45%~55% @50%
1.4. Rise / Fall time (10%~90%)	$\leq 8ns$
1.5. Load	15pF

2. Frequency Stabilities

2.1. Stability vs. operating temp. rang	$\leq \pm 2.8 \times 10^{-7}$	@0°C ~ +70°C ref. to 25 °C
2.2. Initial frequency	$\leq \pm 1.0 \times 10^{-6}$	@25°C
2.3. Stability vs supply voltage change	$\leq \pm 2.0 \times 10^{-7}$	@3.3VDC $\pm 5\%$
2.4. Stability vs Load change	$\leq \pm 1.0 \times 10^{-7}$	@15pF $\pm 5\%$
2.5. Aging	$\leq \pm 2.0 \times 10^{-8}$ / day	
	$\leq \pm 1.0 \times 10^{-6}$ / first year	
	$\leq \pm 3.0 \times 10^{-6}$ / after 10 years	

3. Supply Voltage

3.1. Supply Voltage	+3.3VDC $\pm 5\%$
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4. Current

4.1. Current consumption	$\leq 15mA$
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5. Phase noise (Typical)

5.1. 1KHz	-130dBc/Hz
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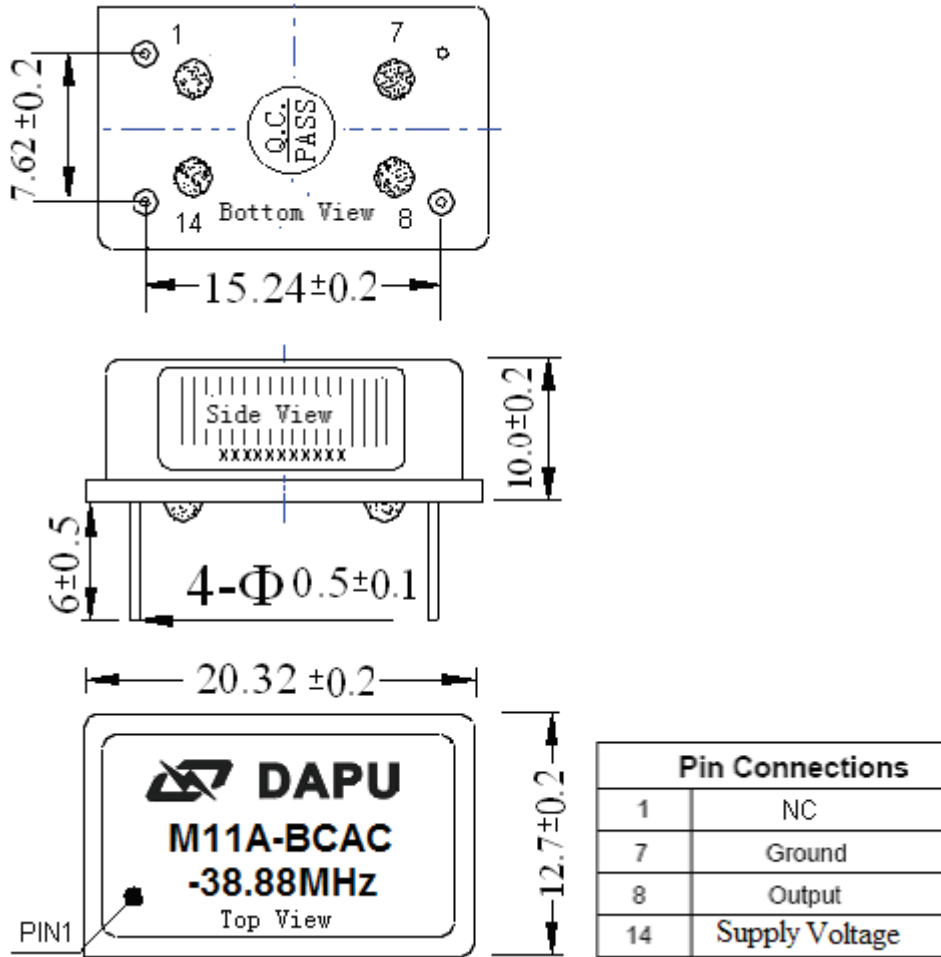
6. Environmental conditions

6.1. Operable temperature range	0°C to +70°C
6.2. Storage temperature range	-50°C to +95°C
6.3. Vibration	IEC 60068-2-6 Test Fc, 10~55Hz, 0.75mm displacement, 30 minutes in each of three mutually perpendicular axes at 1 octave per minute
6.4. Shock	IEC 60068-2-27 Test Ea, 1000m/S ² acceleration for 6ms duration, 3 shocks in each direction along three mutually perpendicular axes.
6.5. Sealing	IEC 60068-2-17 Test Qk (Fine Leak), (MIL-STD-202 Method 112 Test condition C) and IEC 60068-2-17 Test Qc (Gross Leak),(MIL-STD-202 Method 112 Test



condition D)

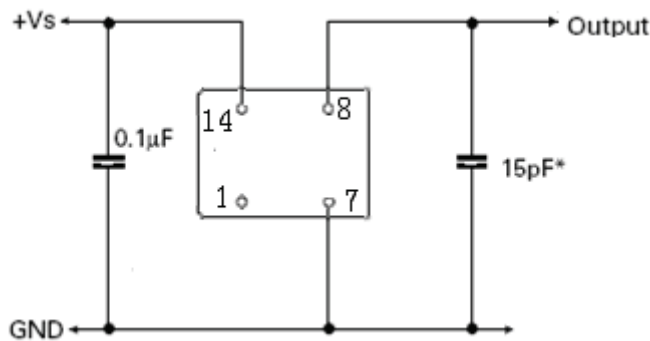
7. Mechanical



Note: The bottom view means that the stitches are against the people

Unit : mm

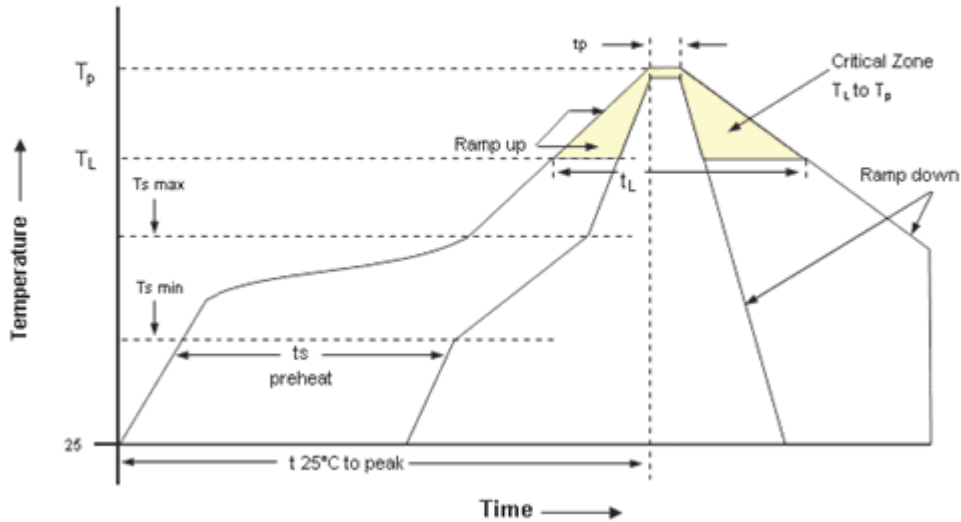
8. Test circuit





9. Recommended Reflow Profile

Solderprofile:



Profile Feature	Pb-Free Assembly	Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_p)	3°C/second max.	Time 25°C to Peak Temperature	8 minutes max.
Preheat -Temperature Min ($T_{s_{min}}$) -Temperature Min ($T_{s_{max}}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds	Time maintained above - Temperature (T_L) - Time (t_L)	217°C 60-150 seconds
$T_{s_{max}}$ to T_L - Ramp-up Rate	3°C/second max.		
Time maintained above - Temperature (T_L) - Time (t_L)	217°C 60-150 seconds	Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Peak Temperature (T_p)	max 260°C	Ramp-down Rate	6°C/second max.

Note: All temperatures refer to topside of the package, measured on the package body surface.